EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	15670	(Sn or tin) near8 powder	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/01 13:55
L2	1760	(silver or Ag or copper or Cu) near8 complex near20 (aryl or alkyl or phosphines or azoles)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/01 13:56
L3	15	1 and 2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/01 13:56
L4	11	3 and ((@ad<"20030415") or (@rlad<"20030415"))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/01 13:56
L5	27858	(silver or Ag or copper or Cu) near20 (aryl or alkyl or phosphines or azoles)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/01 13:58
L7	228	1 and 5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/01 13:59
L8	177	7 and ((@ad<"20030415") or (@rlad<"20030415"))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/01 13:59
L9	181	8 or 3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/01 13:59
L10	9	9 and (solder near bump)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/01 14:39
L11	10	(solder or bump) same (tin near powder) same (aryl or alkyl or azoles)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/01 14:51

L12	10	(solder or bump) and ((tin near powder) same (aryl or alkyl or azoles))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/01 15:01
L13	20	(solder or bump) and (((tin or Sn) near4 powder) same (aryl or alkyl or azoles))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/01 15:04
L14	10	13 not 12	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/01 15:05
L46	2	("6881278").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/05/01 15:45
S2	16	pewter adj paste	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 17:07
S3	1	pewter near8 ((tin adj powder) or (silver adj ions) or (copper adj ions) or (aryl adj phosphines) or (alkyl adj phosphines) or azoles)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/02 16:17
S5	4460724	(substrate or wafer or carrier or board)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/02 16:19
S6	2468167	(electrode or pad or trace)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/02 16:19
S7	2703371	(solder$6 or bump or ball or bond$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/02 16:19
S8	6	((tin or sn) adj powder) with (silver or ag or copper or cu) with (aryl or alkyl or azoles)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/02 16:29
S9	131221	S5 same S6 same S7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/02 16:29

S10	137001	(dam or wall or block) near8 S6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/02 16:31
S11	3410	S10 same S5 same S7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/02 16:32
S12	6142	((438/612) or (438/613) or (438/614) or (438/652) or (438/686)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/02 16:32
S13	117	S11 and S12	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/02 16:33
S14	104	S13 and (((@ad<"20030415") or (@rlad<"20030415"))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/03 09:55
S15	1	("6923875").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/03 09:46
S16	1	pewter same ((tin adj powder) or (silver adj ions) or (copper adj ions) or (aryl adj phosphines) or (alkyl adj phosphines) or azoles)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/03 09:47
S17	6	((tin or sn) adj powder) with (silver or ag or copper or cu) with (aryl or alkyl or azoles)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/03 09:50
S18	2800	(anisotropic adj material)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/03 09:50
S20	0	S18 same (silver or ag or copper or cu) same (aryl or alkyl or azoles)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/03 09:51
S21	97594	anisotropic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/03 09:51

S22	14	S21 same (silver or ag or copper or cu) same (aryl or alkyl or azoles)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/03 09:54
S23	2	S21 same (tin or sn) adj (powder or powdered or powdering))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/03 09:59
S24	16	pewter adj paste	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/03 10:01
S25	2	S24 and (tin or sn)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/03 10:01
S26	16649	((PR or P/R or photoresist or resist or photomask or photo-mask) near8 (electrode or pad or contact) near8 (opening or via or hole or space)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 17:07
S27	1087	S26 same (dam or wall or perimeter)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 17:09
S28	77	S27 same (solder or resin or ball or bond)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 17:09
S29	56	S28 and (((@ad<"20030415") or (@rlad<"20030415"))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 18:01
S30	165	(solder adj resist adj mask)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 18:01
S31	73392	dam	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 18:01
S32	7	S30 and S31	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 18:01

S33	6197	solder adj mask	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 18:01
S34	265	S31 and S33	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 18:01
S35	9952	solder adj resist	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 18:02
S36	301	S31 and S35	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 18:02
S37	4645035	(substrate or wafer or carrier or board)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 18:30
S38	2562505	(electrode or pad or trace)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 18:30
S39	2792601	(solder$6 or bump or ball or bond$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 18:30
S40	142263	(dam or wall or block) near8 S38	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 18:30
S41	3615	S40 same S37 same S39	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 18:30
S42	6420	((438/612) or (438/613) or (438/614) or (438/652) or (438/686)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/02 18:30
S43	123	S41 and S42	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 18:30

S44	107	S43 and ((@ad<"20030415") or (@rlad<"20030415"))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 18:30
S45	73392	dam	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/03 09:54
S46	9952	solder adj resist	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/03 09:54
S47	301	S45 and S46	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/03 09:54
S48	290	S47 and ((@ad<"20030415") or (@rlad<"20030415"))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 17:23
S49	26	dam near8 (PR or P/R or photoresist or resist) near8 (opening or trench or via or hole)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/03 14:12
S50	103	dam near8 photoresist	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/03 14:46
S51	2	("5310574").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/03 14:46
S52	1	("5051339").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/03 14:46
S53	10	("5310574").URPN.	USPAT	OR	ON	2006/02/03 14:47
S54	2	("5738269").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/03 14:47
S55	11	("4339768" | "4413309" | "5024372" | "5043796" | "5133495" | "5261593" | "5395040" | "5400950" | "5477086" | "5558271" | "5598967").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/03 14:49

S56	10	("5738269").URPN.	USPAT	OR	ON	2006/02/03 14:49
S57	7	solder with (tin near powder) with ((silver near ions) or (copper near ions)) with (aryl or phosphines or alkyl or phosphines or azoles)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 17:21
S58	9	("2950184" | "5021269" | "5118029" | "5145532" | "5296649" | "5453582" | "5601228" | "6132646").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/02 17:12
S59	7	solder same (tin near powder) same ((silver near ions) or (copper near ions)) same (aryl or phosphines or alkyl or phosphines or azoles)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 17:21
S60	7	solder same (tin near powder) same ((silver near ions) or (copper near ions)) and (aryl or phosphines or alkyl or phosphines or azoles)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 17:21
S61	7	solder and (tin near powder) same ((silver near ions) or (copper near ions)) and (aryl or phosphines or alkyl or phosphines or azoles)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 17:22
S62	19	solder and (tin near powder) same (silver or copper) and (aryl or phosphines or alkyl or phosphines or azoles)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 17:22
S63	12	S62 not S61	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 17:22
S64	7	S63 and ((@ad<"20030415") or (@rlad<"20030415"))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 17:49
S65	7	solder with (tin or Sn) with powder with (silver or ag or copper or Cu) with ions with (aryl or phosphines or alkyl or phosphines or azoles or benzotriazole)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 17:52
S66	7	solder with (tin or Sn) with powder with (silver or ag or copper or Cu) with ions and (aryl or phosphines or alkyl or phosphines or azoles or benzotriazole)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 17:53

S67	30	solder with (tin or Sn) with powder with (silver or ag or copper or Cu) and ions and (aryl or phosphines or alkyl or phosphines or azoles or benzotriazole)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 17:53
S68	23	S67 not S66	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 17:53
S69	2	("4742020").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/08/03 09:37
S70	4834151	(substrate or wafer or carrier or board)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 14:01
S71	2659156	(electrode or pad or trace)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 14:01
S72	2884838	(solder$6 or bump or ball or bond$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 14:01
S73	147694	(dam or wall or block) near8 S71	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 14:01
S74	3809	S73 same S70 same S72	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 14:01
S75	6714	((438/612) or (438/613) or (438/614) or (438/652) or (438/686)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/08/03 14:01
S76	131	S74 and S75	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 14:01
S77	109	S76 and ((@ad<"20030415") or (@rlad<"20030415"))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 14:02

S78	4	"20020046627"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 14:04
S79	8	(solder near4 precipitat$4 near4 composition) same (tin or Sn or silver or Ag or Copper or Cu) same (aryl or alkyl or azoles)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/30 09:36
S80	4	(("7087563") or ("20040209451")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/04/30 09:58
S81	3	("20040209451" | "6524943" | "7087563").PN. OR ("7291517"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/04/30 10:00
S82	4	("5672542").PN. OR ("6524943").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/04/30 10:14
S83	7	("20040079194" | "5089881" | "5356509" | "5461261" | "5861666" | "6524943" | "6730596").PN. OR ("7119000"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/04/30 10:16
S84	16	((Sn or tin) near4 powder) near8 (Ag or silver or tetrakis) same flux same (heat$4 or anneal$4 or thermal$4) same temperature and (solder or bump)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/30 13:40
S85	6	((tin or Sn) near4 powder) same (silver or Ag or copper or Cu) same (aryl near phosphine) same (alkyl near phosphine) same azoles	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/30 15:24
S86	8	solder same (tin near8 powder) same silver same aryl same alkyl	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/30 15:45
S87	2	S86 not S85	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/30 15:46
S88	4414	(438/612,613).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/04/30 15:59
S89	681	(228/248.1).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/04/30 15:59

S90	3145	(257/772,734,741).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/04/30 16:00
S91	7437	S88 or S90	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/30 16:00
S92	926	(solder same (aryl or alkyl))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/30 16:17
S93	8107	S91 or S89	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/30 16:18
S94	13	S92 and S93	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/30 16:18
S95	25	(solder near8 precipitat$4) same (tin near8 powder) same (salt near8 (lead or pb or copper or cu or silver or ag))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/30 16:39
S96	1010	(solder or bump) same (aryl or alkyl)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/30 16:51
S97	490	S96 same composition	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/30 16:52
S98	267	S97 and ((@ad<"20030415") or (@rlad<"20030415"))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/30 16:52
S99	5	S98 and (tin near8 powder)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/30 16:53
S100	54530	Harima.as.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/30 17:51

S101	14	S100 and (solder near precipitating near composition)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/30 17:51
S102	26	(Knead$4 near8 ((tin or Sn) near4 powder)) same (silver or Ag or copper or Cu)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/01 09:23
S103	87049	(silver or Ag or Cu or copper) same (aryl or alkyl or azoles)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/01 09:31
S104	821	(solder same ((tin or Sn) near4 powder))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/01 09:31
S105	594	S104 and ((@ad< "20030415") or (@rlad< "20030415"))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/01 09:32
S106	29	S103 and S104	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/01 09:32
S107	18	S106 and ((@ad< "20030415") or (@rlad< "20030415"))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/01 09:33
S108	11	(aryl or alkyl) near4 phosphines same azoles	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/01 09:46
S109	10	("2950184" | "5021269" | "5118029" | "5145532" | "5296649" | "5453582" | "5601228" | "6132646").PN. OR ("6923875").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/01 09:48
S110	2	("5145532").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/05/01 09:51

5/ 1/ 2008 3:59:31 PM
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